molex

zSFP+ Stacked PAM4 I/O Connector Solution ❯

zSFP+ Stacked PAM4 I/O Connector Solution, with 2-by-N integrated connectors and cages, delivers data rates of 56 Gbps (100 Gbps for Ethernet) in small spaces while providing improved thermal performance and increased EMI protection

FEATURES AND ADVANTAGES

Improved performance for 56 Gbps PAM4 applications and 100 Gbps for Ethernet
- Provides enhanced thermal performance with through-flow design
- Improved midsection to deliver improved EMI protection

Compact design
Saves space on the PCB

Available with air vents, inner and outer light pipes
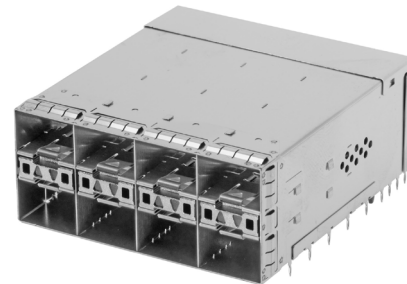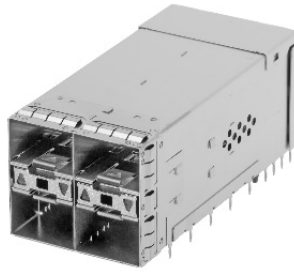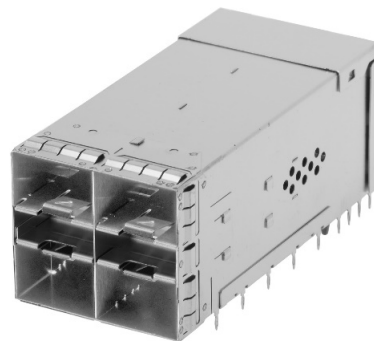Meets various thermal needs and other connectivity requirements

Press-fit insertion
Speeds up assembly time

Drop-in replacement for zSFP+ 28G 2-by-N system
Makes upgrading easier. Reduces necessary design time

A range of available port sizes: 2 by 1, 2 by 2, 2 by 4, 2 by 6, 2 by 8, 2 by 10, and 2 by 12
Offers design flexibility

APPLICATIONS

Data Center Solutions
High-end servers

Telecommunications/ Networking
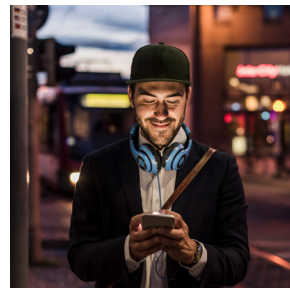Networking equipment
Routers/switches
Servers
Storage
Telecommunications hardware

Servers

Telecommunications Hardware

zSFP+ Stacked PAM4 I/O Connector Solution ❯

SPECIFICATIONS
Stacked PAM4 I/O Integrated Connectors and Cages

REFERENCE INFORMATION
Packaging: Tray
Mates With: zSFP+ Modules
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes

ELECTRICAL
Voltage (max.): 30V AC (RMS) /DC
Current (max.): 0.5A

MECHANICAL
Insertion Force to PCB (max.): 35N
Mating Force (max.): 40N
Unmating Force (max.): 11.5N
Durability (min.): 100 cycles

PHYSICAL
Cage: Nickel Silver
Housing: Glass filled thermoplastic, UL 94V-0, Black
Contact: High-Performance Copper Alloy
Plating:
  Contact Area (min.) — 0.76µ Gold
  Solder Tail Area —0.76 to 1.52µ Matte Tin
  Underplating — Nickel
PCB Thickness (min.): 1.57mm
Operating Temperature: -40 to +85°C

www.molex.com/link/zsfp+.html